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UNITED MICROELECTRONICS CORP  
Form 6-K  
July 17, 2003

1934 Act Registration No. 1-15128

SECURITIES AND EXCHANGE COMMISSION  
Washington, DC 20549

FORM 6-K

REPORT OF FOREIGN PRIVATE ISSUER  
PURSUANT TO RULE 13a-16 OR 15d-16 OF  
THE SECURITIES EXCHANGE ACT OF 1934

Dated July 17, 2003

For the month of June 2003

United Microelectronics Corporation  
(Translation of Registrant's Name into English)

No. 3 Li Hsin Road II  
Science-Based Industrial Park  
Hsinchu, Taiwan, R.O.C.  
(Address of Principal Executive Office)

(Indicate by check mark whether the registrant files or will  
file annual reports under cover of form 20-F or Form 40-F.)

Form 20-F  Form 40-F \_\_\_\_\_  
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(Indicate by check mark whether the registrant by furnishing the  
information contained in this form is also thereby furnishing the information to  
the Commission pursuant to Rule 12g3-2(b) under the Securities Exchange Act of  
1934.)

Yes \_\_\_\_\_ No   
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(If "Yes" is marked, indicated below the file number assigned to the  
registrant in connection with Rule 12g3-2(b): Not applicable )

SIGNATURE

Pursuant to the requirements of the Securities Exchange Act of 1934, the  
registrant has duly caused this report to be signed on its behalf by the

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undersigned, thereunto duly authorized.

United Microelectronics Corporation

Date: 7/17/2003 By /s/ Stan Hung
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Stan Hung
Chief Financial Officer

Exhibit

Table with 2 columns: Exhibit, Description. Contains 5 rows of announcements from June and July 2003.

EXHIBIT 99.1

The Board of Directors Approved a resolution on the Issuance of 2nd Overseas Exchangable Bonds

- 1. Date of the board of directors resolution:2003/06/20
2. Name [\_\_\_\_nth issue of (secured, unsecured) corporate bonds of \_\_\_\_ Co.]:
2nd issue of overseas exchangeable bonds of United Microelectronics Corp.
3. Total amount of the issue: no more than US\$212million
4. Face value: US\$10,000 each or greater
5. Issue price: 101%-108% of par value
6. Issue period: five years
7. Issue coupon/interest rate: authorize the Chairman to decide based on the market condition
8. Types, names, monetary amounts of security or collateral and stipulations thereupon: not applicable
9. Use of the funds raised by the offering and utilization plan: use for overseas material purchase
10. Underwriting method: authorize the Chairman to decide based on the market condition
11. Trustees for the bonds: authorize the Chairman to decide based on the market condition
12. Underwriter or distributing agent institution: authorize the Chairman to decide based on the market condition
13. Guarantor(s) for the issue: not applicable
14. Institution serving as agent for payment of the principal and interest: authorize the Chairman to decide based on the market condition
15. Certifying institution: authorize the Chairman to decide based on the

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market condition

16. Where convertible into shares, the rules for conversion: authorize the Chairman to decide based on the market condition

17. Resale conditions: authorize the Chairman to decide based on the market condition

18. Repurchase conditions: authorize the Chairman to decide based on the market condition

19. The record date for share conversion, if conversion, exchange, or subscription rights are attached: not applicable

20. Possible dilution of equity, if conversion, exchange, or subscription rights are attached: not applicable

21. Any other matters that need to be specified: The exchangeable bonds is subjected to SFC of MOF's approval. Additional announcement will be made thereafter when terms and conditions are finalized.

EXHIBIT 99.2

UMC and HBA Achieve Working 90-nanometer Silicon for HBA's High Speed SRAM

1.Date of occurrence of the event: 2003/07/02

2.Cause of occurrence: Hsinchu, July 2, 2003--UMC, a world leading semiconductor foundry (NYSE: UMC) and High Bandwidth Access, Inc. (HBA), developer of advanced FIFO and specialty memory devices for high capacity broadband networks, today announced the successful prototyping of HBA's high speed IC based on the foundry's 90-nm process. The two engineering teams achieved working silicon on their first pass, signifying the close collaboration between the companies to successfully integrate HBA's design with UMC's most advanced process. Volume production for HBA's IC is expected later this year. UMC's 90-nm HS (High speed) process enables the SRAM prototype to deliver extremely high performance while maintaining a low operational current and a core voltage range of 0.8V-1.4V. The IC paves the way for future SoC integration and is suited for HBA's new high density ZeBL (Zero Bus Latency) SRAM family. In addition, the two companies have validated key analog and digital IPs for UMC's 90-nm process.

3. Countermeasures: none

4. Any other matters that need to be specified: none

EXHIBIT 99.3

SUPERH SH4-202 CPU CORE ACHIEVES SILVER IP STATUS AT UMC

1.Date of occurrence of the event: 2003/07/07

2.Cause of occurrence: Hsinchu, Taiwan; San Jose, USA; Bristol, UK and Tokyo, Japan - 7 July, 2003 UMC (NYSE: UMC) a world leading semiconductor foundry, and SuperH, Inc., the leading supplier of multimedia RISC CPU cores, today announced that SuperH's SH4-202 32-bit CPU core has achieved "Silver IP" status at UMC for the foundry's 0.13um process. A Silver ranking under UMC's Gold IP program signifies that the core has been verified in silicon at UMC and is ready for production.

The SH-4 family is targeted at a wide range of multimedia applications including set top box, car information systems and portable digital consumer products and is supported through SuperH's extensive 3rd party program with over 65 companies offering various development tools, software and design services.

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The "Silver IP" status of the SH4-202 will become "Gold IP" once a customer design that uses the core achieves volume production at UMC. The Gold IP program makes available to customers a wide range of silicon verified IP and library components that are optimized for easy integration into customer designs.

The SH4-202 CPU core integrates a 32-bit RISC CPU core with an integrated Vector floating point unit and delivers an impressive 1.5Dhrystone 2.1 MIPS/MHz and 7MFLOPS/MHz. In 0.13um CMOS the CPU core is less than 1mm2 and the whole hard macro integrating CPU, FPU, 32K D cache, 16K I cache, serial port, timers, real time clock, interrupt controller, bus interface and debug port is only 8.2mm2.

3. Countermeasures:none

4. Any other matters that need to be specified: none

EXHIBIT 99.4

United Microelectronics Corporation

July 9, 2003

This is to report the changes or status of 1) Sales volume 2) Funds lent to other parties 3) Endorsements and guarantees 4) Financial derivative transactions for the period of June 2003

1) Sales volume (NT\$ Thousand)

Period	Items	2003	2002	Changes	%
June	Invoice amount	7,555,783	6,654,217	901,566	13.55%
Jan -June	Invoice amount	41,341,175	33,937,025	7,404,150	21.82%
June	Net sales	7,027,757	6,711,096	316,661	4.72%
Jan -June	Net sales	39,604,152	30,739,328	8,864,824	28.84%

2) Funds lent to other parties (NT\$ Thousand)

Balance as of period end			
	This Month	Last Month	Limit of lending
UMC	0	0	30,949,691
UMC's subsidiaries	30,810	30,367	1,940,958

3) Endorsements and guarantees (NT\$ Thousand)

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	Change in This Month	Balance as of period end	Limit of endorse
UMC	0	0	61,89
UMC's subsidiaries	0	0	
UMC endorses for subsidiaries		0	
UMC's subsidiaries endorse for UMC		0	
UMC endorses for PRC companies		0	
UMC's subsidiaries endorse for PRC companies		0	

4) Financial derivatives transactions

a-1 Hedging purpose (for assets/liabilities denominated in foreign currencies)

Underlying assets / liabilities

Financial instruments

Realized profit (loss)

a-2 Hedging purpose (for the position of floating rate liabilities)

Underlying assets / liabilities

Financial instruments

Realized profit (loss)

b Trading purpose : None

EXHIBIT 99.5

United Microelectronics Corporation  
For the month of June, 2003

This is to report 1) the trading of directors, supervisors, executive officers and 10% shareholders of United Microelectronics Corporation ("UMC") (NYSE : UMC) 2) the pledge and clear of pledge of UMC common shares by directors, supervisors, executive officers and 10% shareholders of UMC 3) the acquisition

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assets by UMC 4) the disposition of assets by UMC for the month of June, 2003

- 1) The trading of directors, supervisors, executive officers and 10% shareholders

Title	Name	Number of shares held when elected (for Directors, Supervisors and Executive Officers) or as May 30, 2001	Number of shares held as of May 31, 2003	Number of shares held as of June 30, 2003
CMO	Chris Chi		3,385,640	3,277,
President	Fu-Tai Liou		5,582,601	5,492,

- 2) The pledge and clear of pledge of UMC common shares by directors, supervisors, executive officers and 10% shareholders :

Title	Name	Number of shares pledge as of May 31, 2003	Number of shares pledge as of June 30, 2003	Changes
N/a	N/a			

- 3) The acquisition assets (NT\$ Thousand)

Description of assets	June	Jan - Jun
Semiconductor Manufacturing Equipment	392,372	3,312,540
Fixed assets	2,132	38,434

- 4) The disposition of assets (NT\$ Thousand)

Description of assets	June	Jan - Jun
Semiconductor Manufacturing Equipment	125,216	993,272

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Fixed assets	0	18,283
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